

### **Features**

- 4.5V-5.5V operation
- · CMOS SRAM for optimum speed and power
- Low active power (165 mW max.)
- Low standby power (L Version)—(110 μW max)
- 2V data retention (L Version)
- JEDEC-compatible pinout
- 32-pin, 0.6-inch-wide DIP package
- . TTL-compatible inputs and outputs

### **Functional Description**

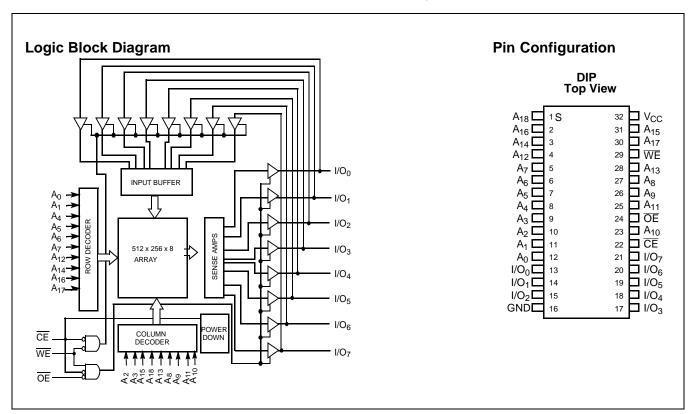
The CYM1465A is a high-performance CMOS static RAM organized as 512K words by 8 bits. Easy memory expansion is provided by an active LOW chip enable (CE), an active LOW Output Enable (OE), and three-state drivers. This device has

# 512K x 8 PDIP Static RAM

an automatic power-down feature that reduces power consumption by more than 99% when deselected.

Writing to the SRAM is accomplished when the chip select  $(\overline{CS})$  and write enable  $(\overline{WE})$  inputs are both LOW. Data on the eight input/output pins  $(I/O_0$  through  $I/O_7)$  of the device is then written into the memory location specified on the address pins  $(A_0$  through  $A_{18})$ . Reading from the device is accomplished by taking chip select (CE) and output enable  $(\overline{OE})$  LOW while write enable  $(\overline{WE})$  remains inactive or HIGH. Under these conditions, the contents of the memory location specified on the address pins  $(A_0$  through  $A_{18})$  will appear on the eight appropriate data input/output pins  $(I/O_0$  through  $I/O_7)$ . The eight input/output pins  $(I/O_0$  through  $I/O_7)$  are placed in a high impedance state when the device is deselected  $(\overline{CE})$  HIGH, the outputs are disabled  $(\overline{OE})$  HIGH, or during a write operation  $(\overline{CE})$  LOW, and  $(\overline{WE})$  LOW).

The CYM1465A is available in a 32-pin 600-mil wide body PDIP package.



### **Selection Guide**

	CYM1465A-70	CYM1465A-85
Maximum Access Time (ns)	70	85
Maximum Operating Current (mA)	20	20
Maximum Standby Current (μA)	20	20



### **Maximum Ratings**

(Above which the useful life may be impaired.)

Storage Temperature ......-55°C to +150°C

Ambient Temperature with

Power Applied......-10°C to +85°C Supply Voltage to Ground Potential.....-0.5V to +7.0V

DC Voltage Applied to Outputs

### DC Input Voltage .....-0.5V to +7.0V

## **Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ± 10%
Industrial	–40°C to +85°C	5V ± 10%

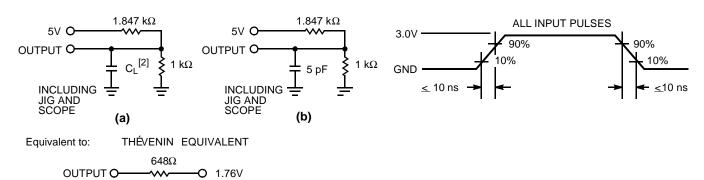
## **Electrical Characteristics** Over the Operating Range

			CYM1465A		
Parameter	Description	Test Conditions	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -1.0 mA	2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub> + 0.3	V
V <sub>IL</sub>	Input LOW Voltage		-0.3	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_I \le V_{CC}$	-1	+1	μΑ
I <sub>OZ</sub>	Output Leakage Current	$GND \le V_O \le V_{CC}$ , Output Disabled	-1	+1	μΑ
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	$V_{CC} = Max., I_{OUT} = 0 \text{ mA}, \overline{CS} \le V_{IL}$		20	mA
I <sub>SB1</sub>	Automatic CS Power-Down Current	Max. $V_{CC}$ , $\overline{CE} \ge V_{IH}$ , Min. Duty Cycle = 100%		1.5	mA
I <sub>SB2</sub>	Automatic CS Power-Down Current	Max. $V_{CC}$ , $\overline{CE} > V_{CC} - 0.3V$ , $V_{IN} > V_{CC} - 0.3V$ or $V_{IN} < 0.3V$		20	μА

## Capacitance<sup>[1]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	8	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.0V$	10	pF

### **AC Test Loads and Waveforms**



### Notes:

- Tested on a sample basis.
- Test conditions assume signal transition times of 10 ns or less, timing reference levels of 1.5V, input levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and 100-pF load capacitance for 85-, 100-, 120-, and 150-ns speeds. C<sub>L</sub> = 30 pF for 70-ns speed.

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## Switching Characteristics Over the Operating Range<sup>[2]</sup>

		CYM14	165A-70	CYM14		
Parameter	Description	Min.	Max.	Min.	Max.	Unit
READ CYCLE		•		•	•	
t <sub>RC</sub>	Read Cycle Time	70		85		ns
t <sub>AA</sub>	Address to Data Valid		70		85	ns
t <sub>OHA</sub>	Data Hold from Address Change	10		10		ns
t <sub>ACE</sub>	CE LOW to Data Valid		70		85	ns
t <sub>DOE</sub>	OE LOW to Data Valid		35		45	ns
t <sub>LZOE</sub>	OE LOW to Low Z	5		5		ns
t <sub>HZOE</sub>	OE HIGH to High Z <sup>[3]</sup>		25		30	ns
t <sub>LZCS</sub>	CE LOW to Low Z	10		10		ns
t <sub>HZCS</sub>	CE HIGH to High Z <sup>[3]</sup>	ıh Z <sup>[3]</sup>			30	ns
t <sub>PU</sub>	CE LOW to Power Down	0		0		
t <sub>PD</sub>	CE HIGH to Power Down		70		85	
WRITE CYCLE <sup>[4]</sup>		<u>.</u>	•	•	•	
t <sub>WC</sub>	Write Cycle Time	70		85		ns
t <sub>SCE</sub>	CE LOW to Write End	60		75		ns
t <sub>AW</sub>	Address Set-Up to Write End	60		75		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		ns
t <sub>PWE</sub>	WE Pulse Width	idth 55		65		ns
t <sub>SD</sub>	Data Set-Up to Write End	30		35		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z	5		5		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[3]</sup>		25		30	ns

### Data Retention Characteristics Over the Operating Range (L Version Only)

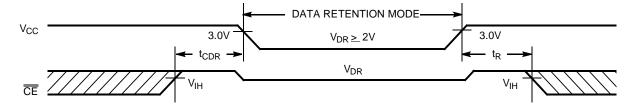
			Commercial		Industrial		
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Unit
V <sub>DR</sub>	V <sub>CC</sub> for Retention Data		2		2		V
I <sub>CCDR3</sub>	Data Retention Current	No Input may exceed		20		20	μΑ
t <sub>CDR</sub> <sup>[5]</sup>	Chip Deselect to Data Retention Time	Vcc+0.3V Vpp = 3.0V	0		0		ns
t <sub>R</sub> <sup>[5]</sup>	Operation Recovery Time	$\begin{array}{l} V_{DR} = 3.0 \text{V}, \\ CE > V_{CC} - 0.3 \text{V}, \\ V_{IN} > V_{CC} - 0.3 \text{V} \text{ or } \\ V_{IN} < 0.3 \text{V} \end{array}$	t <sub>RC</sub>		t <sub>RC</sub>		ns

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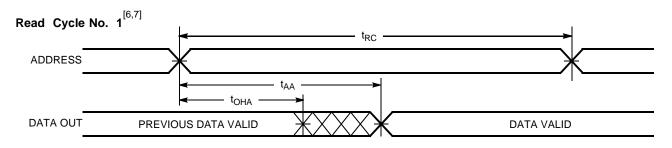
C<sub>L</sub> = 5 pF as in part (b) of AC Test Loads and Waveforms. Transition is measured ±500 mV from steady-state voltage.
 The internal write time of the memory is defined by the overlap of CS LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
 Guaranteed, not tested.

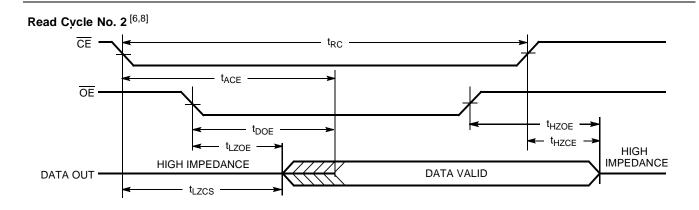


### **Data Retention Waveform**



## **Switching Waveforms**



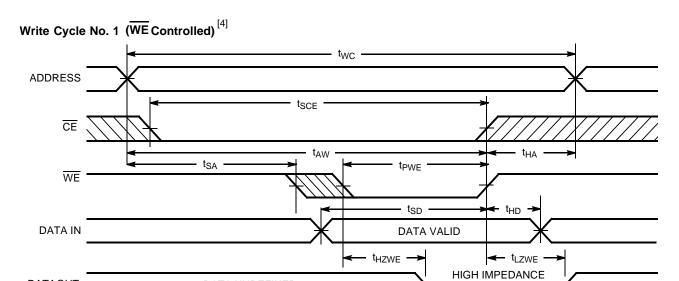


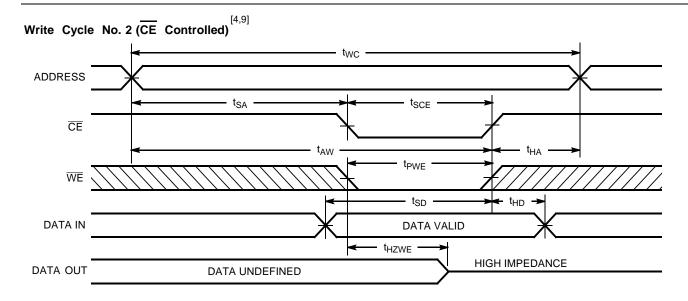
### Notes:

- 6. WE is HIGH for read cycle.
  7. Device is continuously selected, CE = V<sub>|L</sub>.
  8. Address valid prior to or coincident with CE transition LOW.



## Switching Waveforms (continued)





### Note:

9. If  $\overline{\text{CE}}$  goes HIGH simultaneously with  $\overline{\text{WE}}$  HIGH, the output remains in a high-impedance state.

DATA UNDEFINED

## **Truth Table**

DATAOUT

Inputs				
CE	WE	OE	Output	Mode
Н	Х	Χ	High Z	Deselect/Power-Down
L	Н	L	Data Out	Read Word
L	L	Χ	Data In	Write Word
L	Н	Н	High Z	Deselect

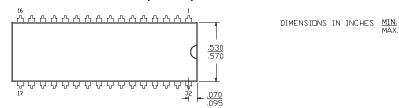


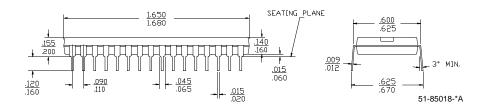
# **Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
70	CYM1465ALPD-70C	P19	32-Pin DIP Module	Commercial
70	CYM1465ALPD-70I	P19	32-Pin DIP Module	Industrial
85	CYM1465ALPD-85C	P19	32-Pin DIP Module	Commercial
85	CYM1465ALPD-85I	P19	32-Pin DIP Module	Industrial

## **Package Diagram**

### 32-Lead (600-Mil) Molded DIP P19







# **Revision History**

Document Title: CYM1465A 512K x 8 PDIP Static RAM Document Number: 38-05269						
REV.	REV. ECN NO. DATE CHANGE DESCRIPTION OF CHANGE		DESCRIPTION OF CHANGE			
**	114171	3/19/02	DSG	Change from Spec number: 38-M-00036 to 38-05269		